



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicant(s):** Kenneth A. Bandy, et al.

**Examiner:** Lan Vinh

**Serial No.:** 10/604,087

**Art Unit:** 1765

**Filed:** June 25, 2003

**Docket:** BUR920020075US1 (16215)

**For:** MULTI-RUN SELECTIVE  
PATTERN AND ETCH WAFER  
PROCESS

**Dated:** June 17, 2005

**Confirmation No.** 1086

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE UNDER 37 C.F.R. §1.111**

Sir:

In response to the Office Action dated February 17, 2005, applicants submit the following amendments and remarks for entry of record in the above-identified patent application.

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**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

**Dated:** June 17, 2005

  
Leslie S. Szivos, Ph.D